

IN THE CLAIMS

Please cancel claim 9.

Please amend the following claims which are pending in the present application:

—What is claimed:

1. (Currently amended) A computer system comprising:
- a frame;
 - a plurality of chassis inserted into the frame;
 - a plurality of electronic components, each on a respective chassis;
 - a plurality of heat-absorbing components mounted for movement with a respective chassis, each located against a respective electronic component and having a component internal volume where a chassis-level fluid is heated;
 - a plurality of thermal components; ~~each thermally coupled to a respective electronic component; and~~
 - a conduit through which the chassis-level fluid flows, whereafter heat transfers from the thermal fluid to a respective chassis-level component; and
 - a fluid-channeling structure on the frame, the fluid-channeling structure having a fluid inlet and a fluid outlet, heat transferring from each of the thermal components to a frame-level fluid after the frame-level fluid enters through the fluid inlet and before the fluid exits out of the frame-level fluid outlet.

*Change - level fluid.
fig 3 or fig 6.*

2. (Currently amended) The computer system of claim 1 wherein each thermal component includes a main structure and a plurality of fins extending from the main structure, over which the frame-level fluid flows.

3. (Original) The computer system of claim 2 wherein the fluid-channeling structure is an air duct.

4. (Currently amended) The computer system of claim 2 wherein the frame-level fluid flows sequentially over successive ones of the thermal components.

5. (Currently amended) The computer system of claim 4 wherein the fins of each respective thermal component are aligned with a direction of flow of the frame-level fluid over the respective thermal component.

6. (Currently amended) The computer system of claim 1 wherein each thermal component has a thermal component internal volume, the frame-level fluid flowing through the thermal component internal volumes.

7. (Currently amended) The computer system of claim 6 wherein the frame-level fluid flows in parallel through the thermal component internal volumes.

8. (Original) The computer system of claim 1 wherein the frame is a support rack frame and the chassis are located above one another in the support rack frame.

9. (Cancelled)

10. (Currently amended) The computer system of claim 9 1 wherein the thermal components are frame components on the frame, further comprising:

a plurality of chassis components, each chassis component being on a respective chassis, being thermally coupled to both a respective electronic component and a respective frame component, the respective chassis being at least partially removable out of the frame, whereafter the respective chassis component is thermally disengaged from the respective frame component.

11. (Original) The computer system of claim 10 wherein the respective chassis component is thermally coupled to the respective electronic component when the respective chassis component is thermally disengaged from the respective frame component.

12. (Original) The computer system of claim 1 wherein the electronic components are processors.

16. (Currently amended) A computer system comprising:

a frame;

a plurality of chassis inserted into the frame;

a plurality of electronic components, each electronic component on a respective chassis;

a liquid inlet;

a plurality of thermal components mounted for movement with a respective chassis, each thermal component being thermally coupled to a respective electronic component, each thermal component having a thermal component internal volume; and

a liquid outlet, a liquid flowing through the thermal component internal volumes after the liquid flows through the liquid inlet but before the liquid flows through the liquid outlet.

17. (Original) The computer system of claim 16 wherein the liquid flows in parallel through the thermal component internal volumes.

18. (Original) The computer system of claim 16 wherein the liquid flows through two chambers in each thermal component.